

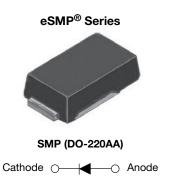
Vishay Semiconductors

AUTOMOTIVE

COMPLIANT HALOGEN

FREE

# Ultrafast Rectifier, 2 A FRED Pt®



#### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	2 A			
V <sub>R</sub>	100 V, 200 V			
V <sub>F</sub> at I <sub>F</sub>	0.79 V			
I <sub>FSM</sub>	40 A			
t <sub>rr</sub> (typ.)	23 ns			
T <sub>J</sub> max.	175 °C			
Package	SMP (DO-220AA)			
Circuit configuration	Single			

#### **FEATURES**

- Very low profile typical height of 1.0 mm
- · Ideal for automated placement
- · Low forward voltage drop, low power losses
- · Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- For PFC, CRM snubber operation
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### TYPICAL APPLICATIONS

For use in high frequency, freewheeling, DC/DC converters, PFC, and in snubber industrial and automotive applications.

#### **MECHANICAL DATA**

Case: SMP (DO-220AA)

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per

J-STD-002, meets JESD 201 class 2 whisker test

Polarity: color band denotes cathode end

ABSOLUTE MAXIMUM RATINGS						
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS	
VS-2ENH01HM3		V		100		
Peak repetitive reverse voltage	VS-2ENH02HM3	$V_{RRM}$		200	, v	
Average rectified forward current		I <sub>F(AV)</sub>	T <sub>C</sub> = 158 °C	2	Α	
Non-repetitive peak surge current		I <sub>FSM</sub>	T <sub>J</sub> = 25 °C, 10 ms sine pulse	40	A	
Operating junction and storage temperatures		T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C	

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage,	VS-2ENH01HM3	V <sub>BR</sub> ,	I <sub>R</sub> = 100 μA	100	-	-	V
blocking voltage	VS-2ENH02HM3	$V_{BR}, \ V_{R}$		200	-	-	
Forward voltage		V	I <sub>F</sub> = 2 A	-	0.94	1.00	]
		V <sub>F</sub>	I <sub>F</sub> = 2 A, T <sub>J</sub> = 150 °C	-	0.79	0.84	
Reverse leakage current			$V_R = V_R$ rated	-	-	2	μA
		IR	T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	-	20	
Junction capacitance		C <sub>T</sub>	V <sub>R</sub> = 200 V	-	8	-	pF

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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST COI	MIN.	TYP.	MAX.	UNITS	
		$I_F = 1.0 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	23	-	
Reverse recovery time t <sub>rr</sub>	t <sub>rr</sub>	$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_{rr} = 0.25 \text{ A}$		-	-	28	1
		T <sub>J</sub> = 25 °C		-	16	-	ns
	T <sub>J</sub> = 125 °C		-	25	-		
Peak recovery current I <sub>RRM</sub>		T <sub>J</sub> = 25 °C	$I_F = 2 A$ $dI_F/dt = 200 A/\mu s$ $V_R = 100 V$	-	2.0	-	A
	IRRM	$T_{\rm J} = 125  ^{\circ}{\rm C}$		-	3.1	-	
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	15	-	nC
Theverse recovery charge	very charge Q <sub>rr</sub>	T <sub>J</sub> = 125 °C		-	37	-	110

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range		T <sub>J</sub> , T <sub>Stg</sub>		-55	-	175	°C
Thermal resistance, junction to mount		R <sub>thJM</sub> <sup>(1)</sup>	Infinite heatsink	-	7	9	°C/W
Thermal resistance, junction to ambient		R <sub>thJA</sub>	PCB footprint 4.8 mm x 4.8 mm	-	107	-	C/VV
Approximate weight					0.024		g
Marking device VS-2ENH01HM3   VS-2ENH02HM3			Coop at the CMAD (DO 2004A)	2H1			
			Case style SMP (DO-220AA)	2H2			

#### Note

<sup>(1)</sup> Thermal resistance junction to mount follows JEDEC® 51-14 transient dual interface test method (TDIM)

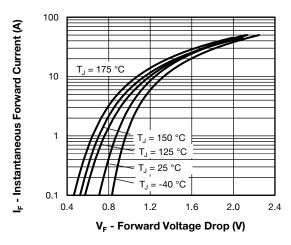


Fig. 1 - Typical Forward Voltage Drop Characteristics

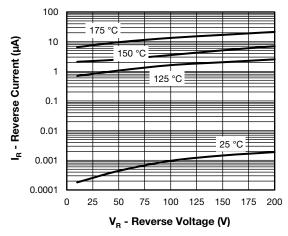


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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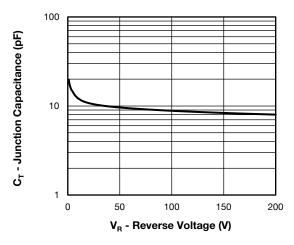


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

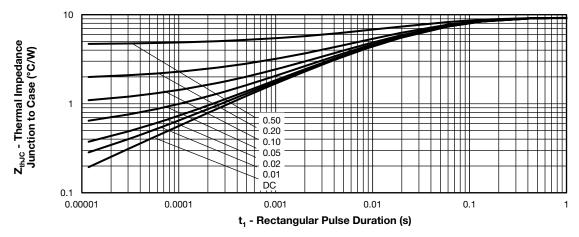


Fig. 4 - Transient Thermal Impedance, Junction to Case

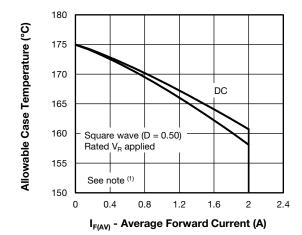


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

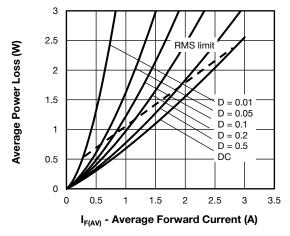


Fig. 6 - Forward Power Loss Characteristics

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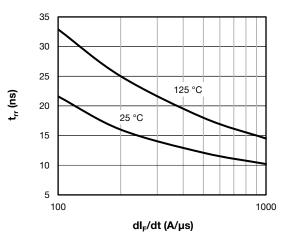


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

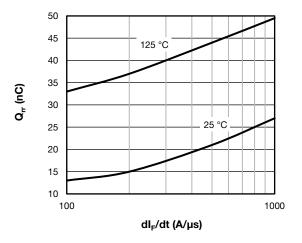
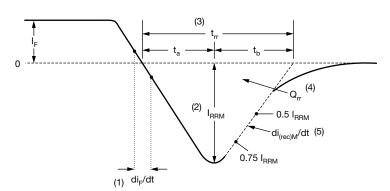


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $^{(1)}$  Formula used: T<sub>C</sub> = T<sub>J</sub> - (Pd + Pd<sub>REV</sub>) x R<sub>thJC</sub>; Pd = forward power loss = I<sub>F(AV)</sub> x V<sub>FM</sub> at (I<sub>F(AV)</sub>/D) (see fig. 5); Pd<sub>REV</sub> = inverse power loss = V<sub>R1</sub> x I<sub>R</sub> (1 - D); I<sub>R</sub> at V<sub>R1</sub> = rated V<sub>R</sub>



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{RRM}$  peak reverse recovery current
- (3)  $t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through 0.75  $I_{RRM}$  and 0.50  $I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{rr}$  area under curve defined by  $\mathbf{t}_{rr}$  and  $\mathbf{I}_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

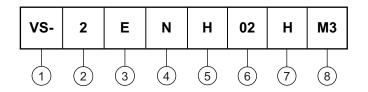
(5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

Fig. 9 - Reverse Recovery Waveform and Definitions

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#### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

2 - Current rating (2 = 2 A)

- Circuit configuration:

E = single diode

4 - N = SMP package

Process type,

H = ultrafast recovery

6 - Voltage code (02 = 200 V)

7 - H = AEC-Q101 qualified

M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	PREFERRED PACKAGE CODE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-2ENH01HM3/84A	84A	3000	7" diameter plastic tape and reel			
VS-2ENH01HM3/85A	85A	10 000	13" diameter plastic tape and reel			
VS-2ENH02HM3/84A	84A	3000	7" diameter plastic tape and reel			
VS-2ENH02HM3/85A	85A	10 000	13" diameter plastic tape and reel			

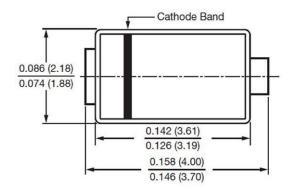
LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?96547</u>					
Part marking information	www.vishay.com/doc?96574				
Packaging information	www.vishay.com/doc?88869				
SPICE model	www.vishay.com/doc?96551				

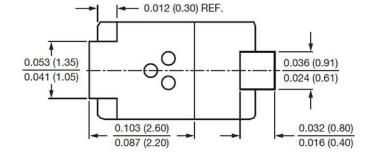


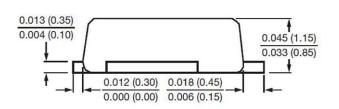
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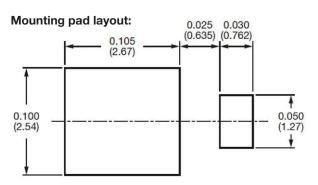
# **SMP (DO-220AA)**

### **DIMENSIONS** in inches (millimeters)











### **Legal Disclaimer Notice**

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